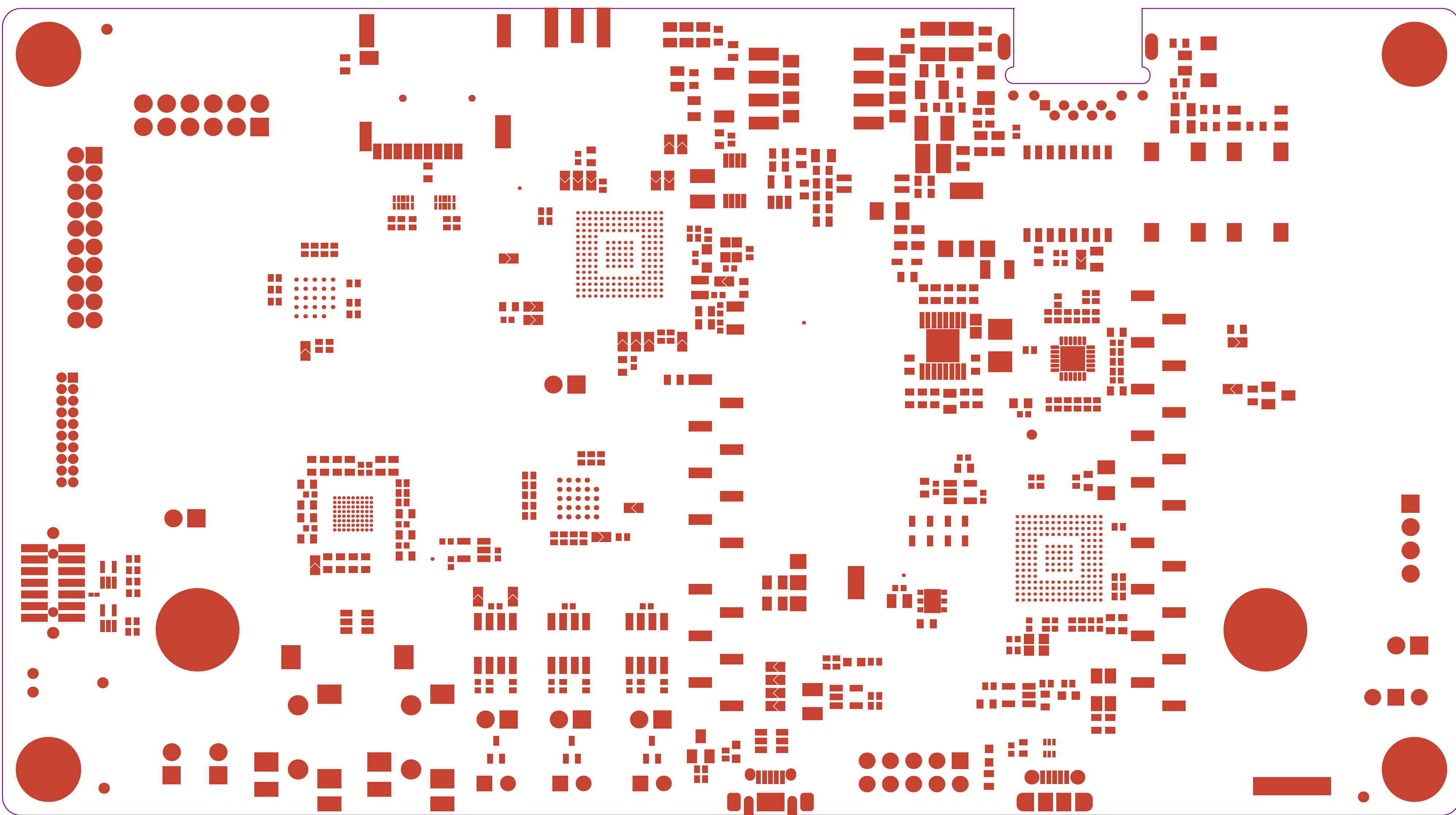


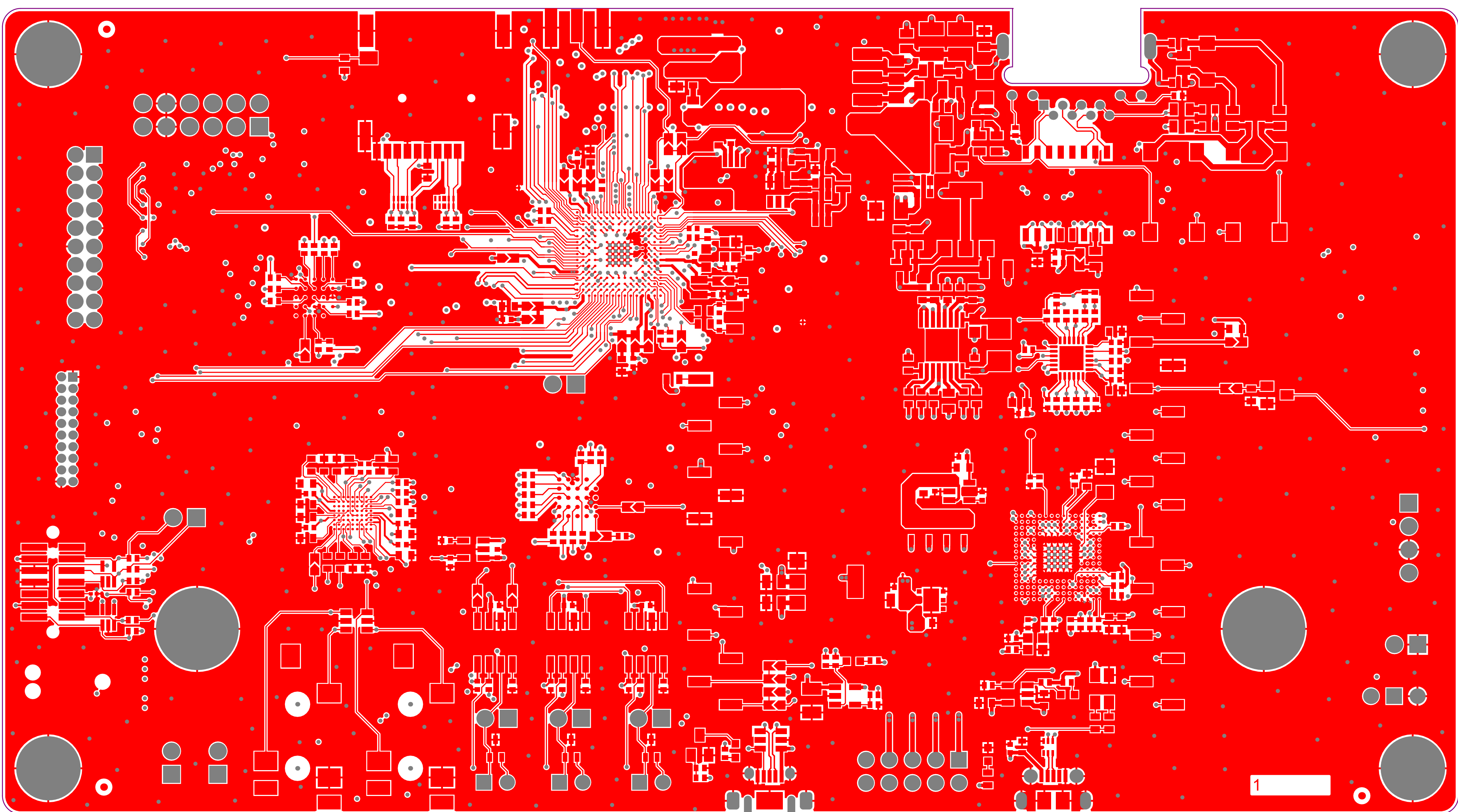


.GTO



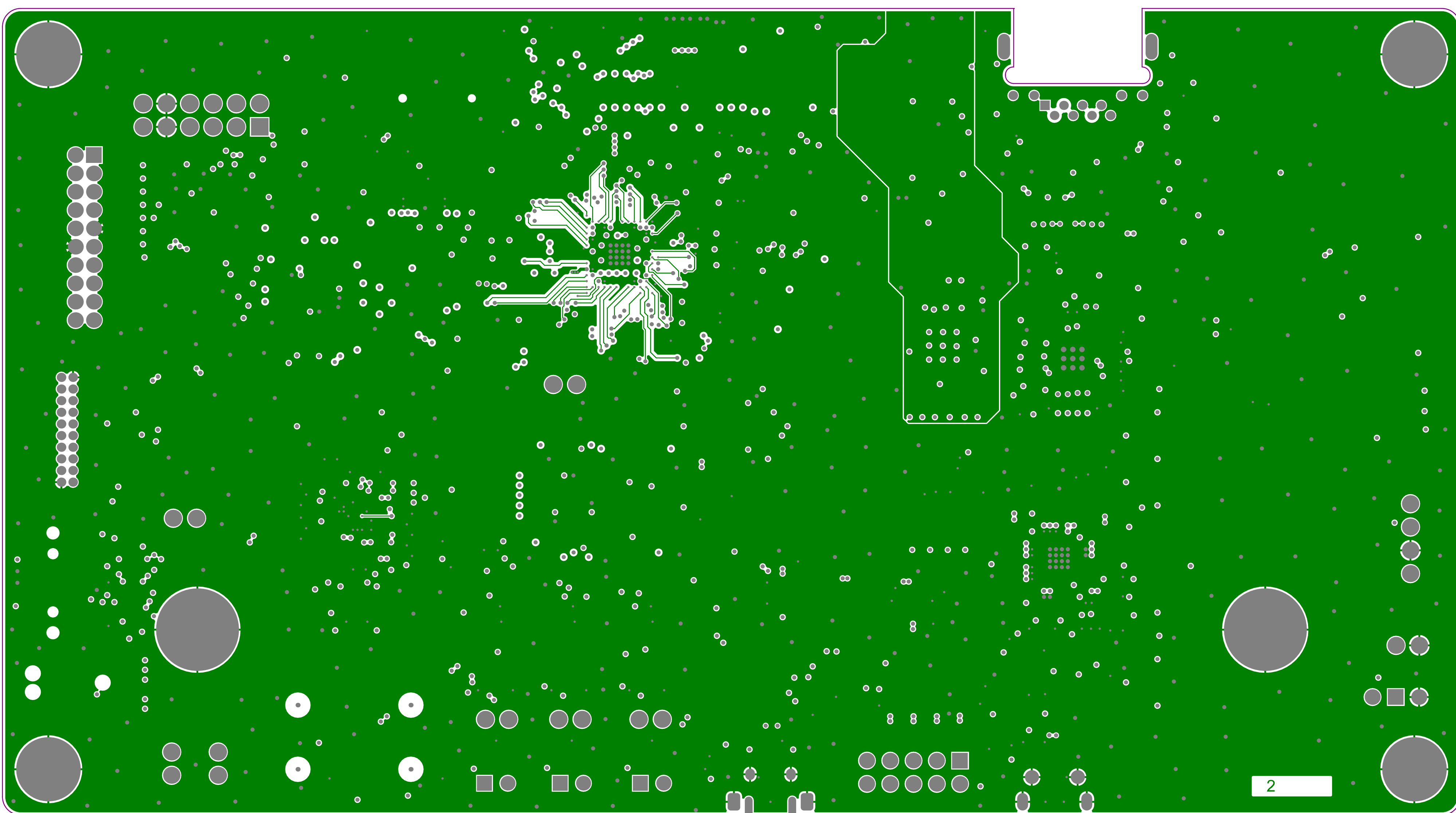
Top Solder

.GTS



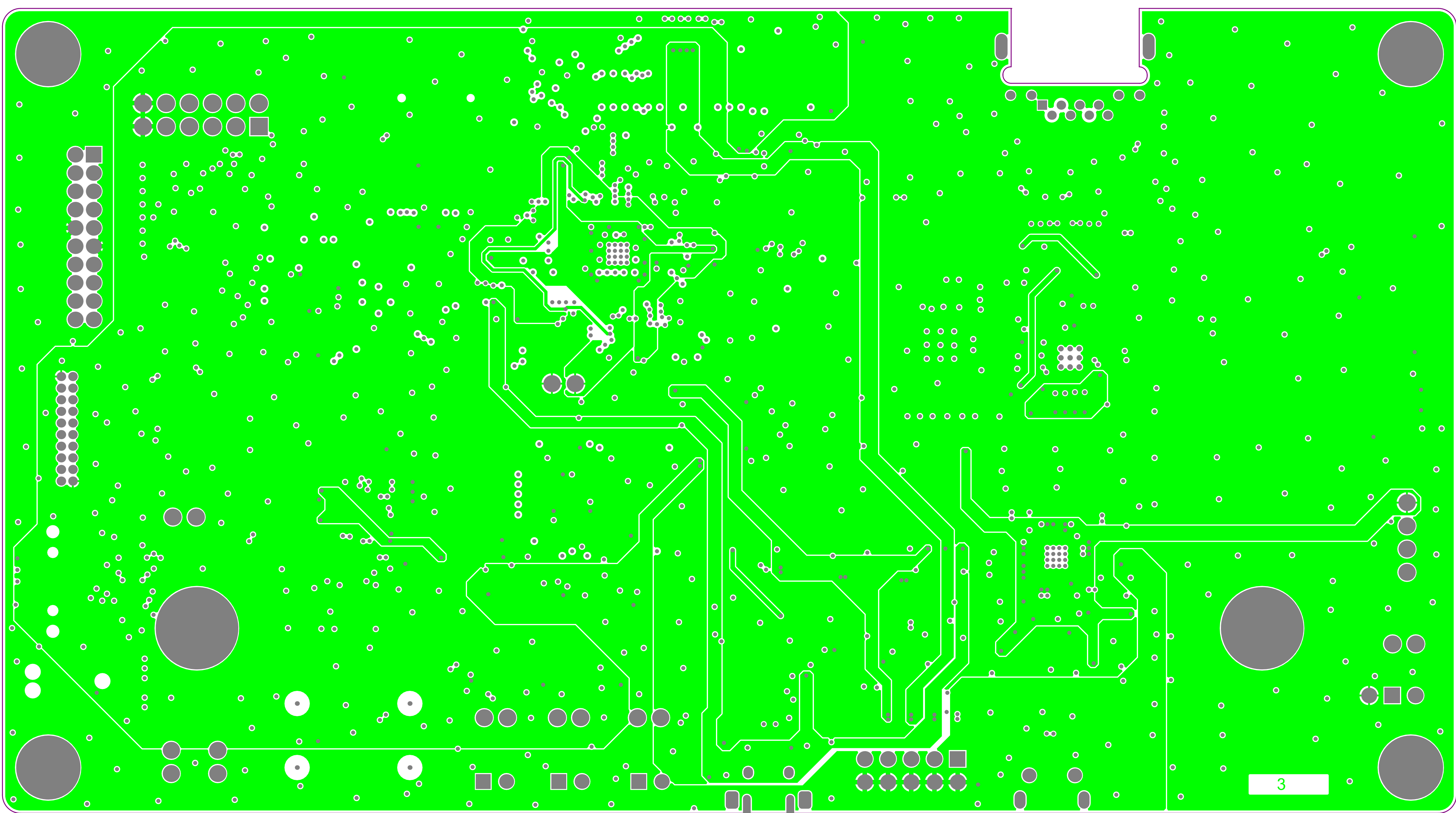
Top Layer

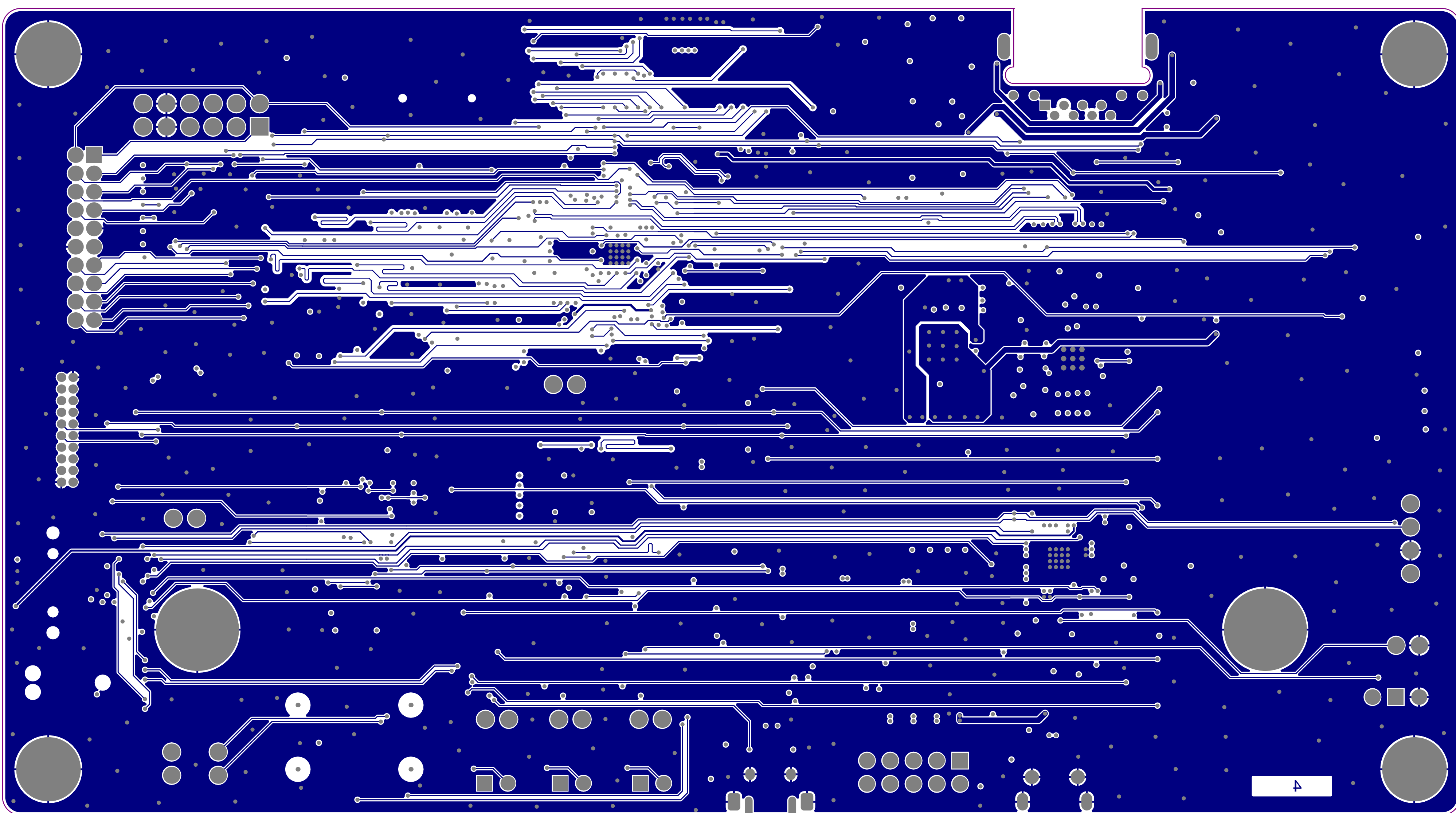
.GTL

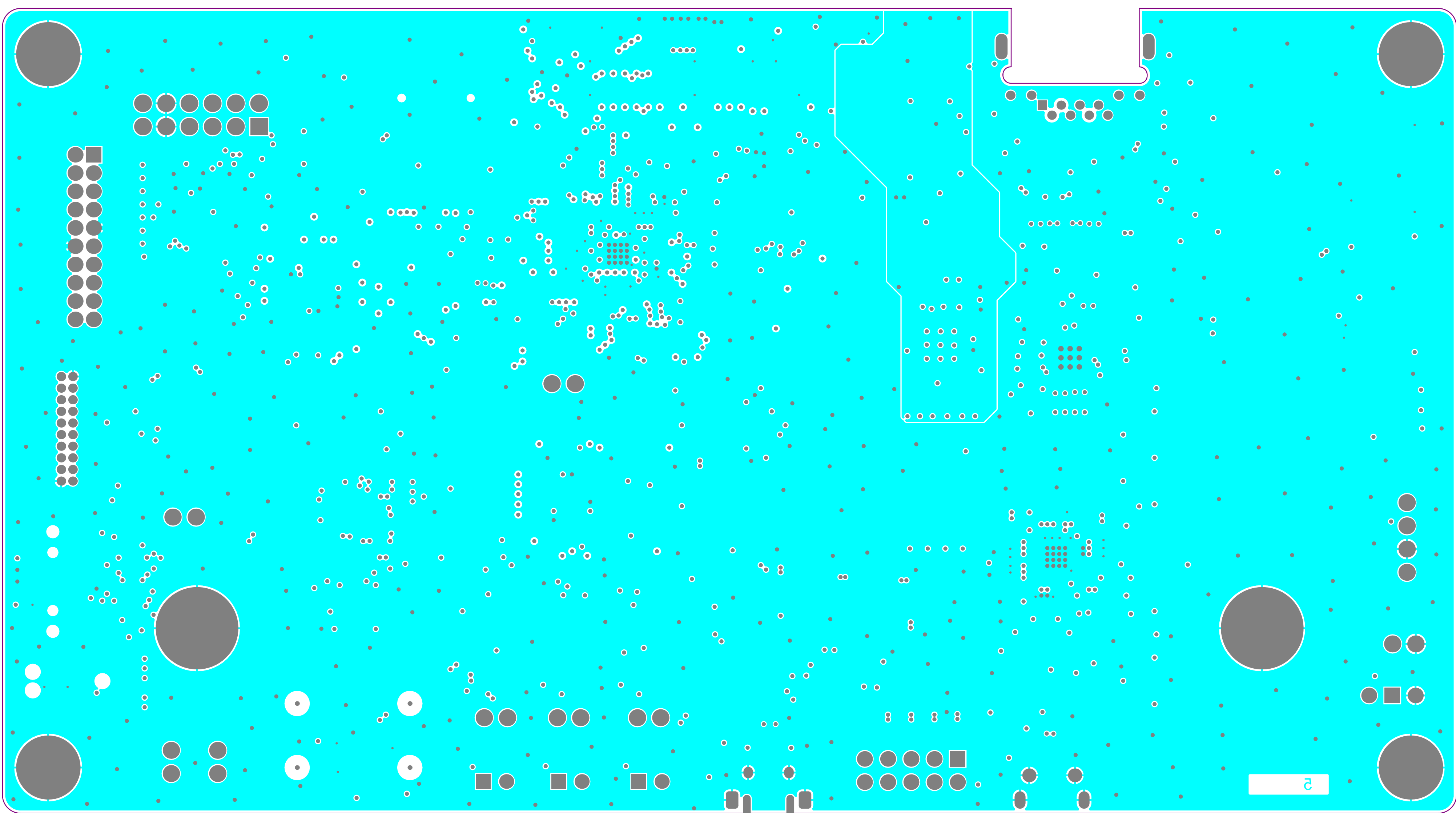


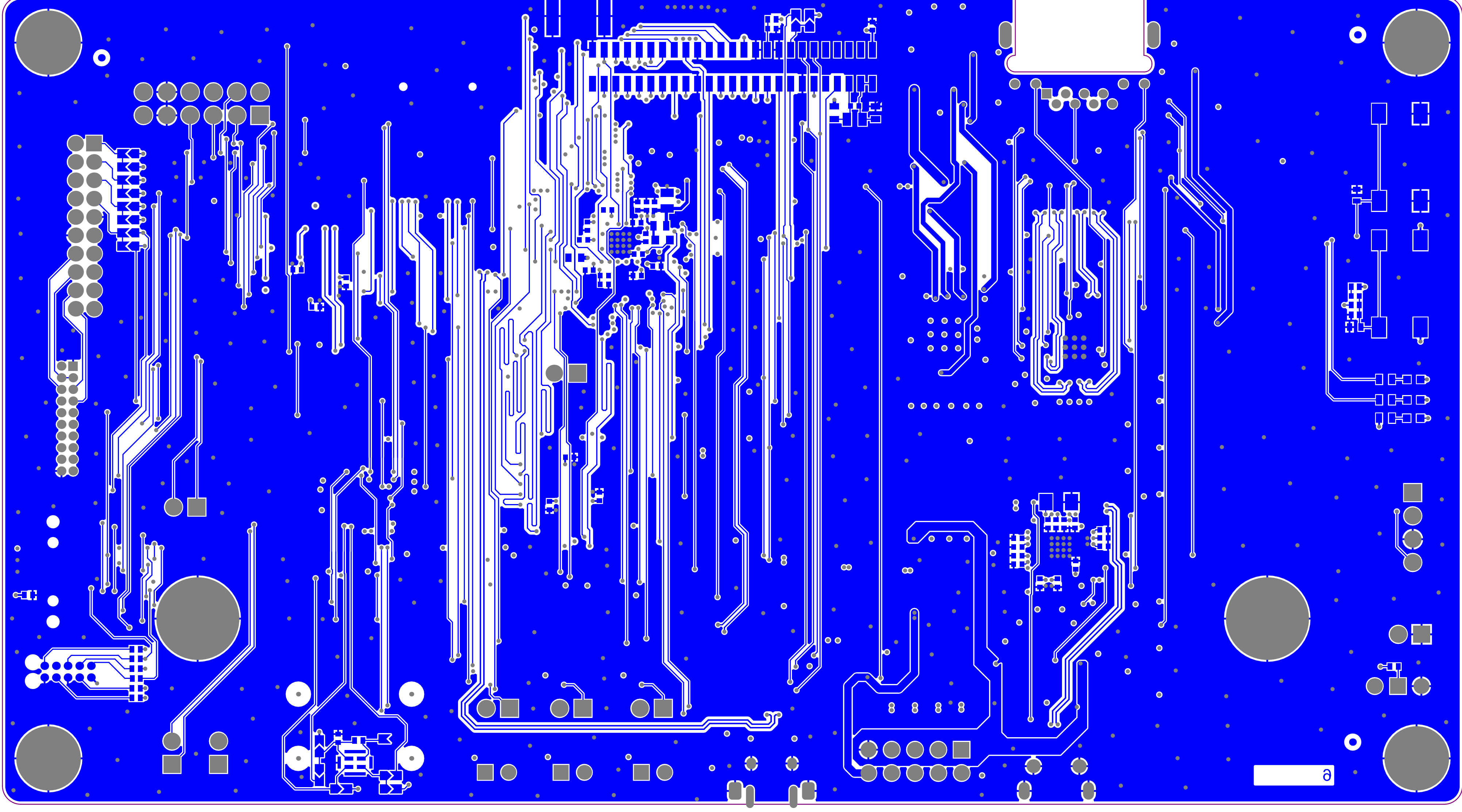
Signal Layer 1

.G1

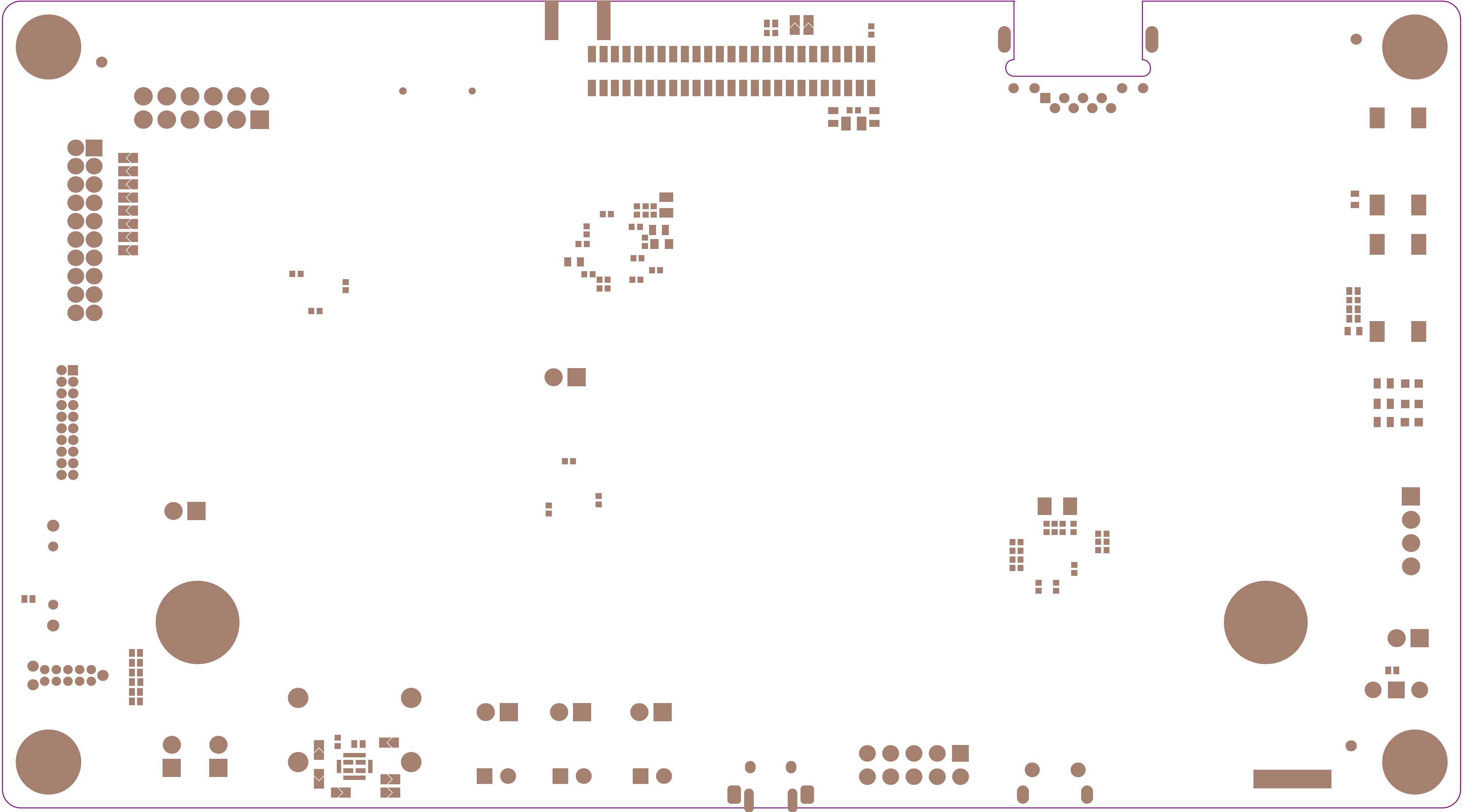








Bottom Layer
.GBL



.GBS

Bottom Solder



PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ TG-150

☐ TG-140

☐ WHITE

☒ BLUE

☐ BLACK

☐ Blue ink PANTONE 2955

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL (PB-FREE)

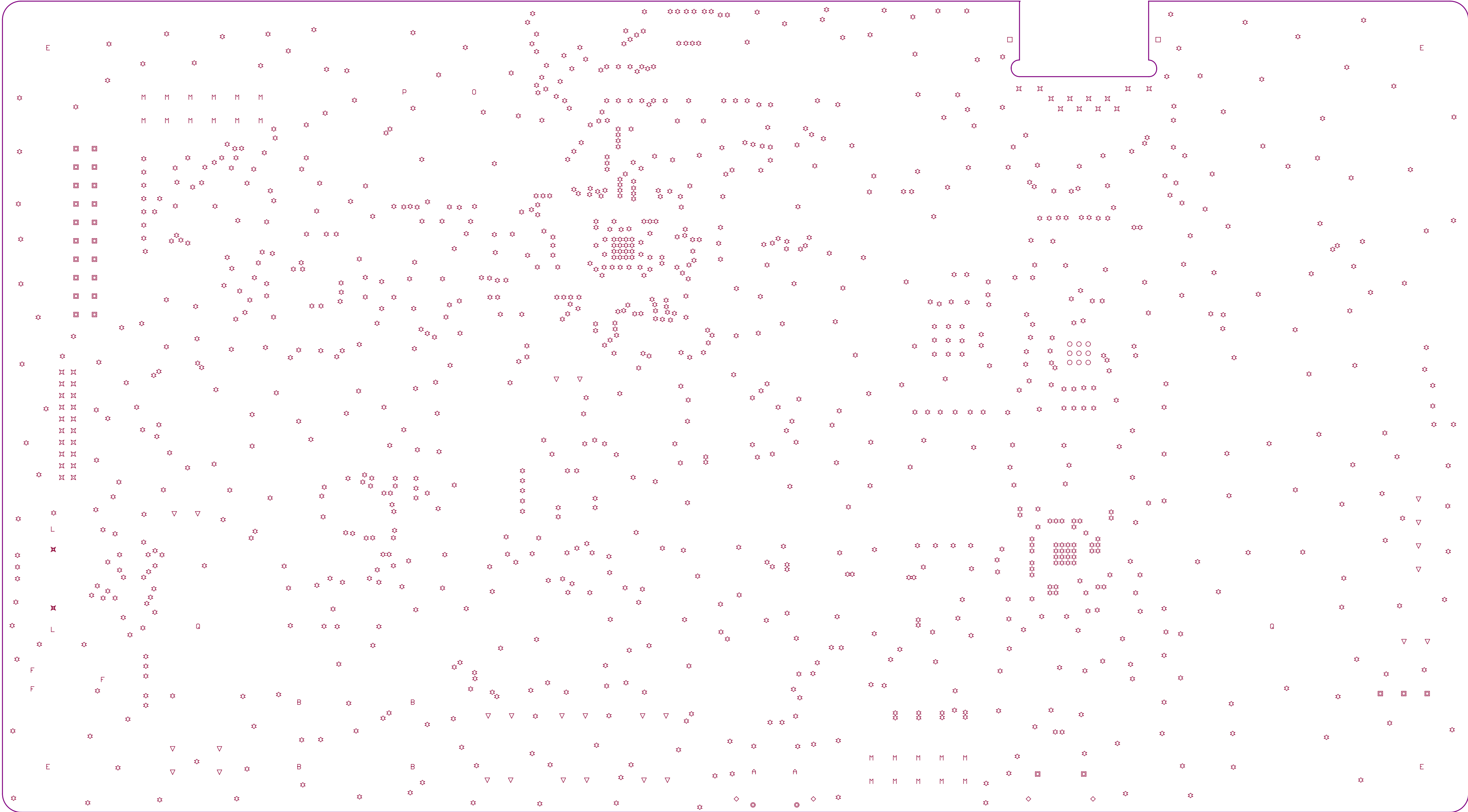
☐ GOLDEN FINGER

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »



PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.12mm
GAPS : 0.12mm

MCU / BGA
TRACKS : 0.09mm
GAPS : 0.08mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,015mm	3,5	
3	Top Layer	Copper	0,042mm		
4	Dielectric1	FR-4	0,099mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2		0,102mm	4,2	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3	FR-4	0,946mm	4,2	
9	Signal Layer 3	Copper	0,035mm		
10	Dielectric 4		0,102mm	4,2	
11	Signal Layer 4	Copper	0,035mm		
12	Dielectric 5	FR-4	0,099mm	4,2	
13	Bottom Layer	Copper	0,042mm		
14	Bottom Solder	Solder Resist	0,015mm	3,5	
15	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
☆	1099	0,20mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
○	9	0,30mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
◇	4	0,60mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1,30mm (51,18mil)	0,70mm (27,56mil)
⌒	2	0,65mm (25,59mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	0,85mm (33,47mil)	0,20mm (7,88mil)
○	1	0,65mm (25,59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
P	1	0,70mm (27,56mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
✱	32	0,70mm (27,56mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	2	0,70mm (27,56mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	2,20mm (86,61mil)	1,50mm (59,06mil)
◎	2	0,85mm (33,47mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	2,42mm (95,47mil)	1,57mm (62,01mil)
▣	25	0,90mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
✱	2	0,97mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	26	1,00mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
F	3	1,10mm (43,31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
M	22	1,10mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
L	2	1,19mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
B	4	2,00mm (78,74mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
E	4	3,50mm (137,80mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
Q	2	4,50mm (177,17mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	1242 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout